



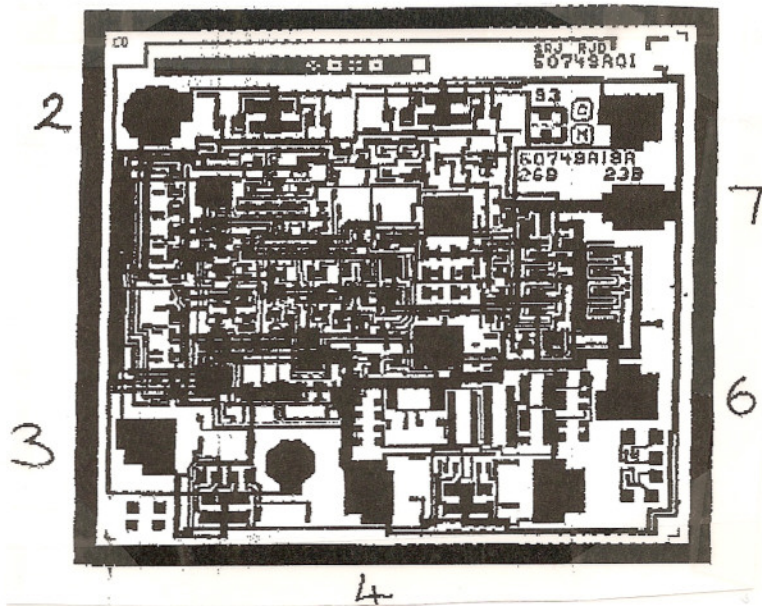
Sierra Components, Inc.

2222 Park Place Building 3 Suite E • Minden, Nevada 89423

Phone: 775.783.4940 Fax: 775.783.4947

Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

| Pad | Function |
|-----|----------|
| 1 | NC |
| 2 | -IN |
| 3 | +IN |
| 4 | V- |
| 5 | NC |
| 6 | OUT |
| 7 | V+ |
| 8 | NC |



NOTE: The chip back potential is unbiased, ie floating. However Harris recommends that the chip back be connected to V-.

Topside Metal: Al
Backside: Si
Backside Potential:
Mask Ref: 50749
Bond Pads: .004" min

APPROVED BY:CB
MFG: HARRIS

DIE SIZE: .059" x .059"
THICKNESS: .019"

DATE: 1/26/01
P/N: HFA1105